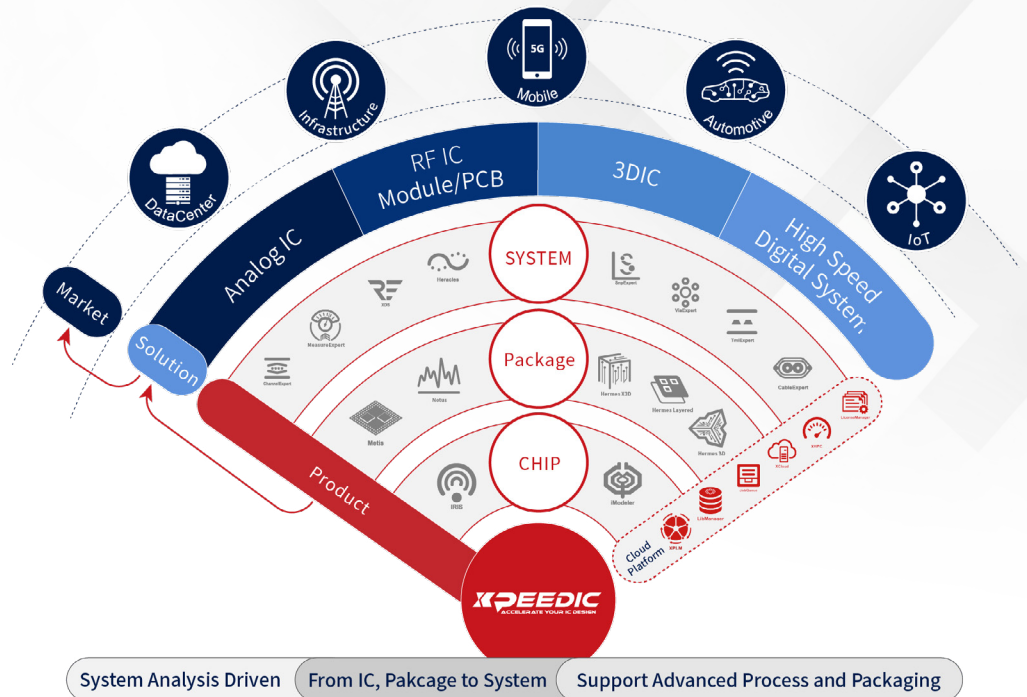


Xpeedic Simulation EDA for IC-Package-System



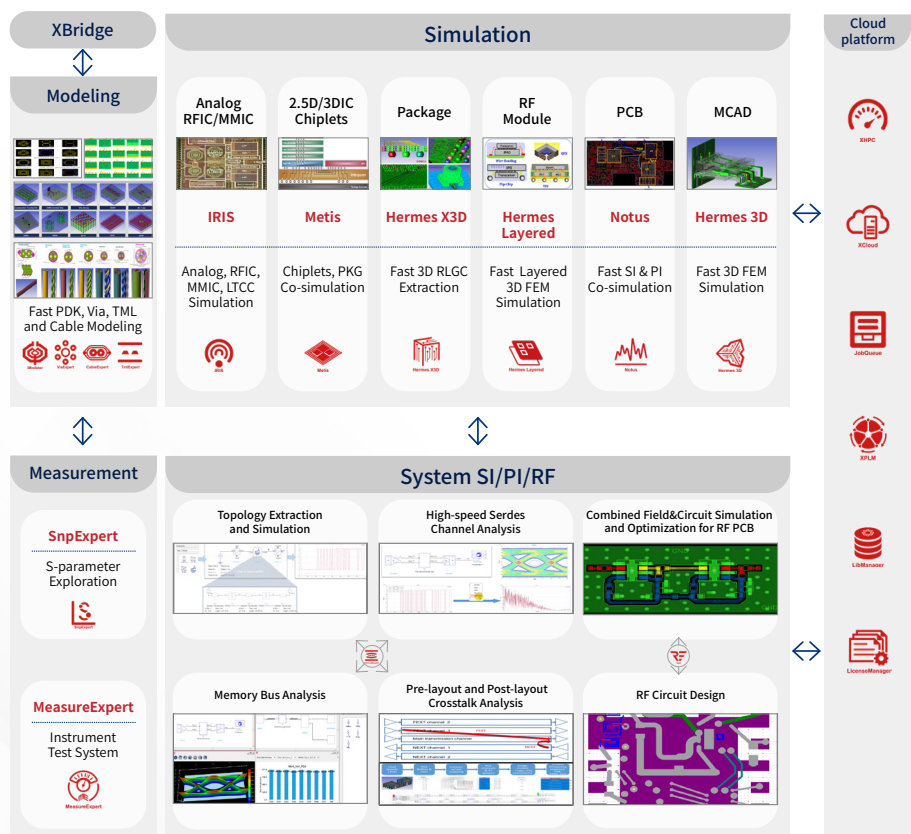
Xpeedic EDA Overview

Support advanced process and packaging to enable next-generation integrated system



Xpeedic EDA Product Family

Modeling, Simulation, Analysis, Measurement, Cloud

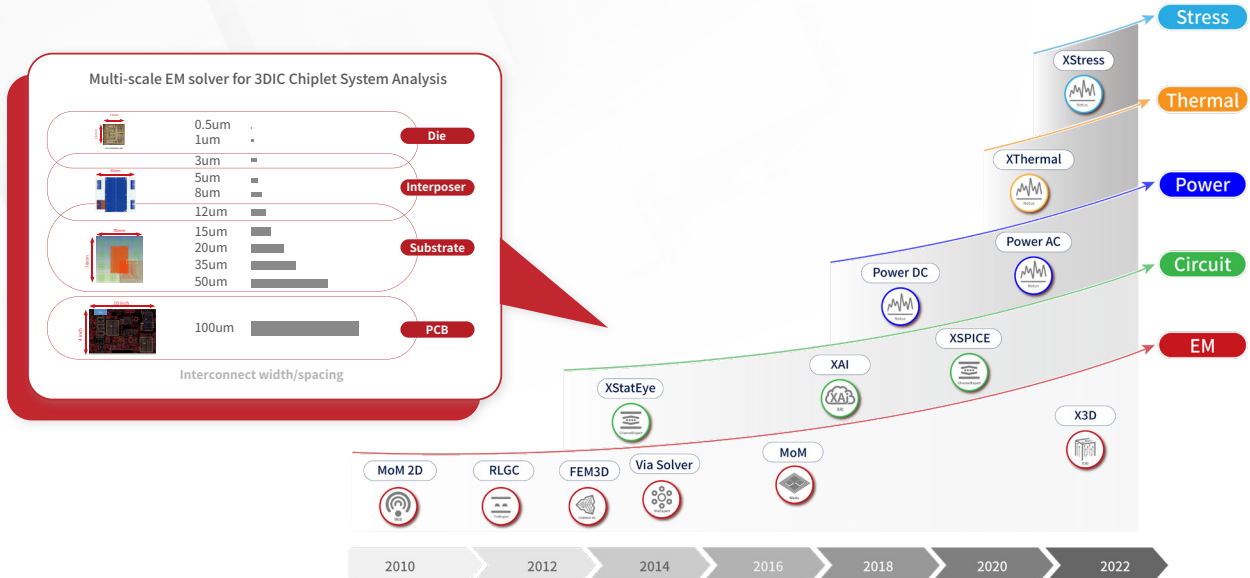


Xpeedic EDA Core Technologies

1

Industry Leading Solver Technology

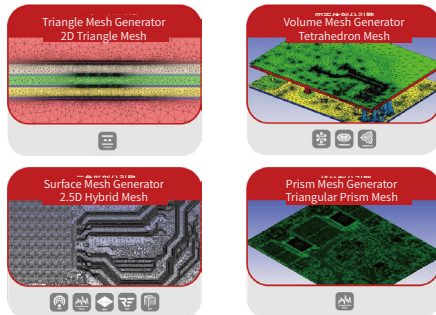
Multi physics solver technology from circuit, electromagnetic, thermal to stress simulation



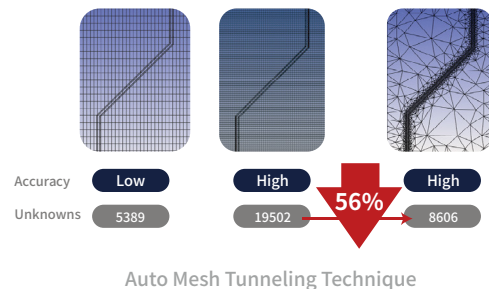
2

AI-based Mesh Technology

Multiple Adaptive Mesh Technology For Different Application Scenarios



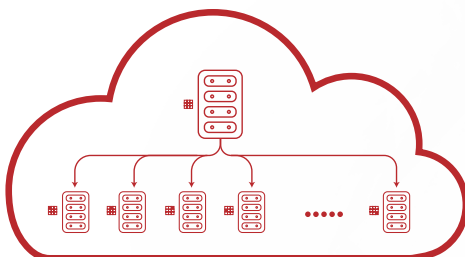
Convergent Results With Minimum Number Of Mesh Elements



3

High Performance Distributed Parallel Computing Technology

Matrix-level Distributed Parallel Computing By MPI



Success Cases: Use Metis for Advanced Packaging Simulation
Result: Metis delivers 10X simulation speed comparing to the other tools.

